1. T1 does not use a washer or insulator. It is soldered to the pads as shown in the component layout in Figure 5.

2. The 22pf capacitor on the input of T1 as shown in the schematic diagram is not used.

3. The thermistor, R9, mounts below the PC board touching the heatsink. Use thermo-compound to ensure good heat transfer from the heatsink to the thermistor. The hole location for R9 is shown in the upper left corner of the PC board as shown in the Component Layout in Figure 5.

4. The inductors L1 and L2 are short pieces of #20 AWG wire used to connect R14 and R15 from the pads under T1 to the end of T2. See Component Layout in Figure 5.

5. R3 is adjusted to about twice the FET gate voltage which is around 7 to 8 volts.

6. The end of T2 which is opposite the end where T2 is mounted on the metal clad mica capacitors should be elevated. Copper spacers can be used.